



YES-CV200RFL Plasma Strip/Descum System

Powerful Cleaning Removes Photoresist, Polyimide and BCB;
With Gentle Descum Function

Specifications

Hardware	
Clean Room Compatibility	Class 10
Wafer Temperature Range	Ambient to 300 °C
Capacity	Single wafer/pieces for 50mm - 200mm
Process Gas Inputs	4 standard
Mass Flow Controllers	Optional, up to 4 for gas mixing
Interior Chamber Dimensions	25.4 cm (W) x 28.575 cm (D) x 4.978 cm (H) (10" x 11.25" x 1.96")
Hot Plate Process Area	49 in ² maximum (200mm wafer)
Overall System Dimensions	50.8 cm (W) x 144.78(D) x 190.5 cm (H) (20" x 57" x 75")
Chamber Material	6061-T6 aluminum
Compliance	SEMI S2, CE, S8
Software	
PC	Monitor with pull out keyboard and automation control
Number of Recipes	12 with load/save/loop/link capability
Data Collection	YES-DAQ standard, SECS/GEM required
Performance	
Power	200-250 VAC, 40 amps (estimated)
Descum Specifications	
• Handling Speed	30 sec/wafer
• Min. Process Time and Temp	10-30 seconds
• Minimum Etch Rate	200Å/min
• Uniformity (Gallium)	Within Wafer: +/- 4% Wafer to Wafer: +/- 5% Lot to Lot: +/- 5%
• Uniformity (Silicon)	Within Wafer: +/- 4% Wafer to Wafer: +/- 5% Lot to Lot: +/- 5%
Etch Specifications	
• Minimum Process Time	30 Seconds - 2 minutes, assuming 20000 Å photoresist
• Minimum Etch Rate	7000Å/min @ 200°C, higher at 300°C
• Uniformity	Within Wafer: +/- 10% Wafer to Wafer: +/- 10% Lot to Lot: +/- 10%
Additional	
Power Requirements	200-250V, 20 amps, 50/60 Hz, 1 phase
Power Supply	Automatic frequency tuning



Contact Us

When you're ready to run process tests, a demonstration can be arranged using your chemicals and samples. Call +352 450010 or visit us at www.bitalu.lu

©2012 Yield Engineering Systems. Yield Engineering Systems and the Yield Engineering Systems logo are trademarks of Yield Engineering Systems, Inc. All other brands, product names and logos are trademarks or service marks of their respective owners. All specifications subject to change without notice. Individual process results may vary.